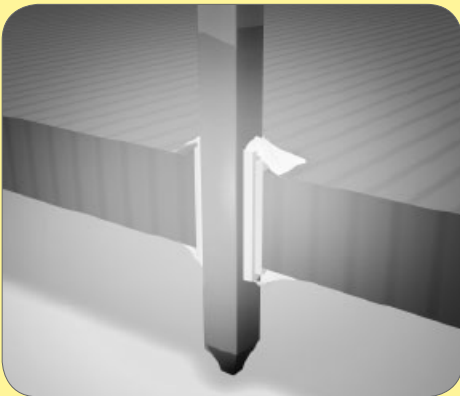
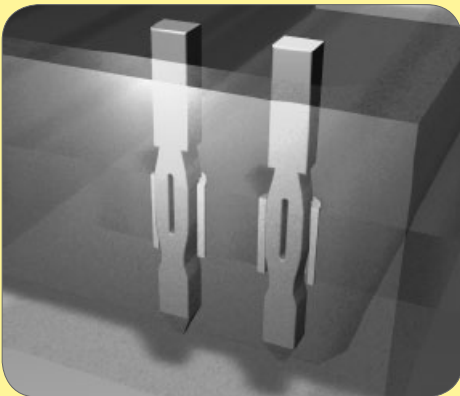


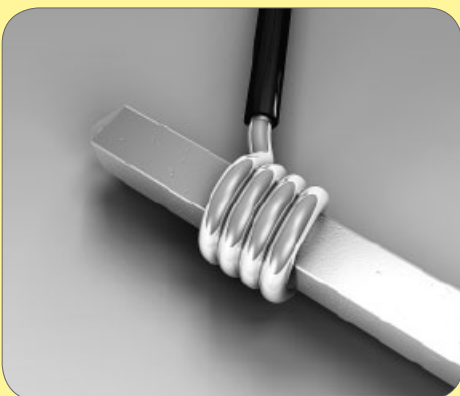
THT soldering technology



SMC soldering technology



Press-in technology



Wire wrap terminals

### THT soldering technology

Proven over decades, standard soldering technologies deliver maximum stability and process reliability. The soldering pins of the connectors are inserted into the through-plated PCB holes and can then be soldered simultaneously with other components in a wave soldering process.

### SMC soldering technology

The connector is inserted into through-plated PCB holes similar to standard component assembly for processing with SMC (Surface Mount Compatible) soldering technology. Insertion of these SMT components can be automated by means of Pick & Place assembly in preparation for a reflow soldering process together with the surface-mounted component.

This connection technology is characterized by high mechanical strength and is facilitated by a design that is specially adapted to the reflow soldering process (high-temperature materials).

### Press-in technology

This solder-free connection technology is based on press-in mounting of a pin in a throughplated PCB hole. The implementation of a state-of-the-art, flexible press-fit zone allows for the compensation of tolerances of PCB holes and meets high electrical and mechanical requirements for properties such as low press-in forces and high holding forces.

Press-in technology supports unlimited cost efficient processing, especially of pins with selective gold plating for backplane bus systems.

### Wire wrap terminals

This solder-free connection technology is based on a wire, which is wrapped with several turns onto a rectangular post. When wires are correctly wrapped the connection performs with low resistance, mechanical strength and high reliability, unaffected by normal climatic or temperature change.